ABSTRACT OF THE DISCLOSURE

A method for imaging a semiconductor wafer includes the steps of preparing a mask that is formed with at least first and second mask patterns, positioning the mask on an exposure system, positioning the wafer on the exposure system, forming a first image, which corresponds to the first mask pattern, on the wafer, removing the wafer from the exposure system, subjecting the wafer to subsequent integrated circuit forming steps, repositioning the wafer on the exposure system, and forming a second image, which corresponds to the second mask pattern, on the wafer.